

INTERNATIONAL STANDARD

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**Mechanical standardization of semiconductor devices –
Part 6-12:
General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
Design guide for fine-pitch land grid array (FLGA) –
Rectangular type**

Normalisation mécanique des dispositifs à semiconducteurs –

*Partie 6-12:
Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
pour montage en surface –
Guide de conception pour les boîtiers FLGA
de type rectangulaire*

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –**Part 6-12: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
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Rectangular type**

FOREWORD

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The text of this standard is based on the following documents:

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

A bilingual version of this publication may be issued at a later date.

The committee has decided that the contents of this publication will remain unchanged until 2004. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

INTRODUCTION

The demand for area array style packages exists because of the multi-functions and high performance of electrical equipment. The objective of this design guide is to standardize outlines and to get interchangeability of FLGA rectangular type packages. The terminal pitch and package outlines of these fine-pitch array packages are smaller than those of LGA packages.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

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1 Scope

This part of IEC 60191 provides common outline drawings and dimensions for all types of structures and composed materials of fine-pitch land grid array (hereinafter called FLGA) whose terminal pitch is less than, or equal to, 0,80 mm and whose package body outline is rectangular.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191 (all parts), *Mechanical standardization of semiconductor devices*